

Technical specifications

Hybrid 5

Maximum output per hour	165 k (121k IPC 9850A)
Maximum output per hour for flip chip bonding (IPC 9850)	10.5 - 16 k with dipping 13.5 - 27 k without dipping
Placement quality	< 1 dpm
Placement accuracy @ CpK1	25 µm for passives 18 µm for QFP/BGA/FC 7 µm for flip chips ¹
Minimum component size (LxW):	0.25 x 0.125 mm (0201m)
Maximum component size (LxW):	45 x 45 mm (1.77 x 1.77")
Maximum component height:	10.5 mm (0.41")
- Optional	12 mm (0.47")
Placement force range	0.5 to 8 N
Maximum board size (LxW):	
- Standard	515 x 390 mm (20.28 x 15.35")
- Optional	800 x 457 mm (31.5 x 18")
Minimum board size (LxW):	
- Standard	50 x 50 mm (2 x 2")
- Optional	50 x 25 mm (2 x 1")
Maximum optional board length	800 mm (31.5")
Maximum optional board width	508 mm (20")
Board thickness:	
- Standard	0.3 to 6 mm (0.01 to 0.24")
- Optional	≥ 0.05 mm
Automatic toolbit exchange	Nozzles
Maximum tape feeding positions (8mm):	
Single lane feeders	130
Twin tape feeders	260
Feeding options (special feeders on request)	Tape, waffle pack, tray, wafer, others
Footprint excl. feeders (LxW)	3,720 x 1,705 mm (146.46 x 67.13")

For extended specifications, not specified in these tables, please call your local Kulicke & Soffa contact.